WHAT IS CLAIMED IS:

1.   A multibeam exposure apparatus which exposes a substrate by using a plurality of charged-particle beams, comprising:

5   a deflection member which deflects an incident position of each of the plurality of charged-particle beams on the substrate;

a generation member which generates pattern data to be projected onto the substrate; and

10   a correction member which corrects a positional error of each of the plurality of charged-particle beams by said deflection member and said generation member.

2.   The apparatus according to claim 1, wherein when

15   each of the plurality of charged-particle beams is deflected to a predetermined exposure position on the basis of the pattern data, said correction member corrects a static positional error independent of a deflection position by said deflection member, and

20   corrects a dynamic positional error dependent on the deflection position by said generation member.

3.   A multibeam exposure method of exposing a substrate by deflecting each of a plurality of charged-particle beams to a predetermined exposure

25   position, comprising:

a first correction step of correcting a positional error of each of the plurality of

charged-particle beams by independently deflecting a

position of each of the plurality of charged-particle

beams; and

a second correction step of correcting the

5 positional error of each of the plurality of

charged-particle beams by generating pattern data to be

projected onto the substrate.

4. The method according to claim 3, wherein in the

first correction step, a static positional error

10 independent of a deflection position is corrected when

each of the plurality of charged-particle beams is

deflected to a predetermined exposure position on the

basis of the pattern data, and in the second correction

step, a dynamic positional error depending on the

15 deflection position is corrected.

5. A method of manufacturing a device by using an

exposure method defined in claim 3.

6. An exposure apparatus which exposes a substrate

by using a plurality of charged-particle beams on the

20 basis of pattern data, comprising:

a deflector array which deflects an incident

position of each of the plurality of charged-particle

beams on the substrate so as to correct a first

component out of the positional error of each of the

25 plurality of charged-particle beams; and

a controller which generates the pattern data so

as to correct a second component out of the positional

error of each of the plurality of charged-particle
beams.

7.   The apparatus according to claim 6, further
comprising a main deflector which deflects the
5   plurality of charged-particle beams at once,

wherein the first component contains a static
distortion independent of deflection by said main
deflector, and the second component contains a dynamic
distortion dependent on the deflection by said main
10   deflector.

8.   A device manufacturing method comprising steps
of:

exposing a substrate by using an exposure
apparatus defined in claim 6; and
15   developing the exposed substrate.